ASDCIATION CONNECTING ELECTRONICS (MOUSTRIES*) MOUSTRIES*	ourn. Illinois. All rights reserved u	Inder both This do level p	ocument is a declara arts, the declaration	tion of the subs encompasses a	stances within the ll lower level mate	manufacturer liste erials for which th	ed item. Note: le manufacture	if the item is an as er has engineering	sembly with lower responsibility.		
IPC Web Site for Information on I http://www.ipc.org/IPC-175x	PC-1752 Standard	Form Type * Distribute		Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia				als and Mfg Information			
Supplier Information											
Company name*	Company unique ID			Unique ID Authority				Response Date*			
onsemi								2025-06-08			
Contact Name	Title - Contact		Phone - Cont	Phone - Contact*			Email - Contact*				
Product-Env-Stewards	Product Enviro Compliance		NA	NA			Product-Env-Stewards@onsemi.com				
Authorized Representative*	Title - Representative		Phone - Representative*			Ema	Email - Representative*				
Product-Env-Stewards Product Enviro Compliance			NA			Proc	Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr Item	n Number Mfr Item Name	Mfr Item Name		e Version	Manufactur	Manufacturing Site		UOM	Unit Type		
NCP114	ASN150T1G 300 mA CMOS L Vout=1.5V	DO, AD option,	2025-06-08		MY1		13.65	mg	Each		
Manufacturing Proccess Information											
Terminal Plating / Grid Array Material	Ferminal Base Alloy	J-STD-020 MSL Rating	g Peak Pro	Peak Process Body Temperature		me at Peak Temp	erature Num	ber of Reflow Cyc	eles		
Matte Tin (Sn) - annealed CU Alloy 1		1	260	C	C 30	se	conds 3				
Comments											
evel 1 - maximum time at peak temperature during so	Idering is 10-30 seconds										
For more information regarding material composition	please refer to page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DIP).								
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted				
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all				
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the				
Supplier Digital Signature Ra	stislav Drska	Le							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.12	mg	Supplier	Silicon (Si)	7440-21-3		0.12	mg
Lead Frame 5.1	5.78	mg	Supplier	Silver (Ag)	7440-22-4		0.526	mg
			В	Nickel (Ni)	7440-02-0		2.127	mg
			Supplier	Iron (Fe)	7439-89-6		2.9189	mg
			Supplier	Copper (Cu)	7440-50-8		0.2081	mg
Mold Compound-Black 7.34	7.34	mg		Epoxy resin	proprietary data		0.367	mg
			Supplier	Phenolic Resin	Proprietary Data		0.367	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.1468	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0367	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.4225	mg
Plating	0.39	mg	Supplier	Tin (Sn)	7440-31-5		0.39	mg
Wire Bond - Cu	0.02	mg	Supplier	Copper (Cu)	7440-50-8		0.02	mg